

**/ Descriptions**

SOT-23          NPN                          Silicon NPN transistor in a SOT-23 Plastic Package.

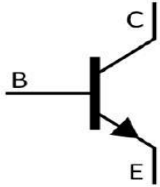
**/ Features**

, BC327M  
High current, complementary pair with BC327M.

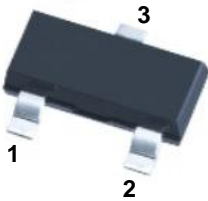
**/ Applications**

General power amplifier and switching.

**/ Equivalent Circuit**



**/ Pinning**



PIN1 Base          PIN 2 Emitter          PIN 3 Collector

**/  $h_{FE}$  Classifications & Marking**

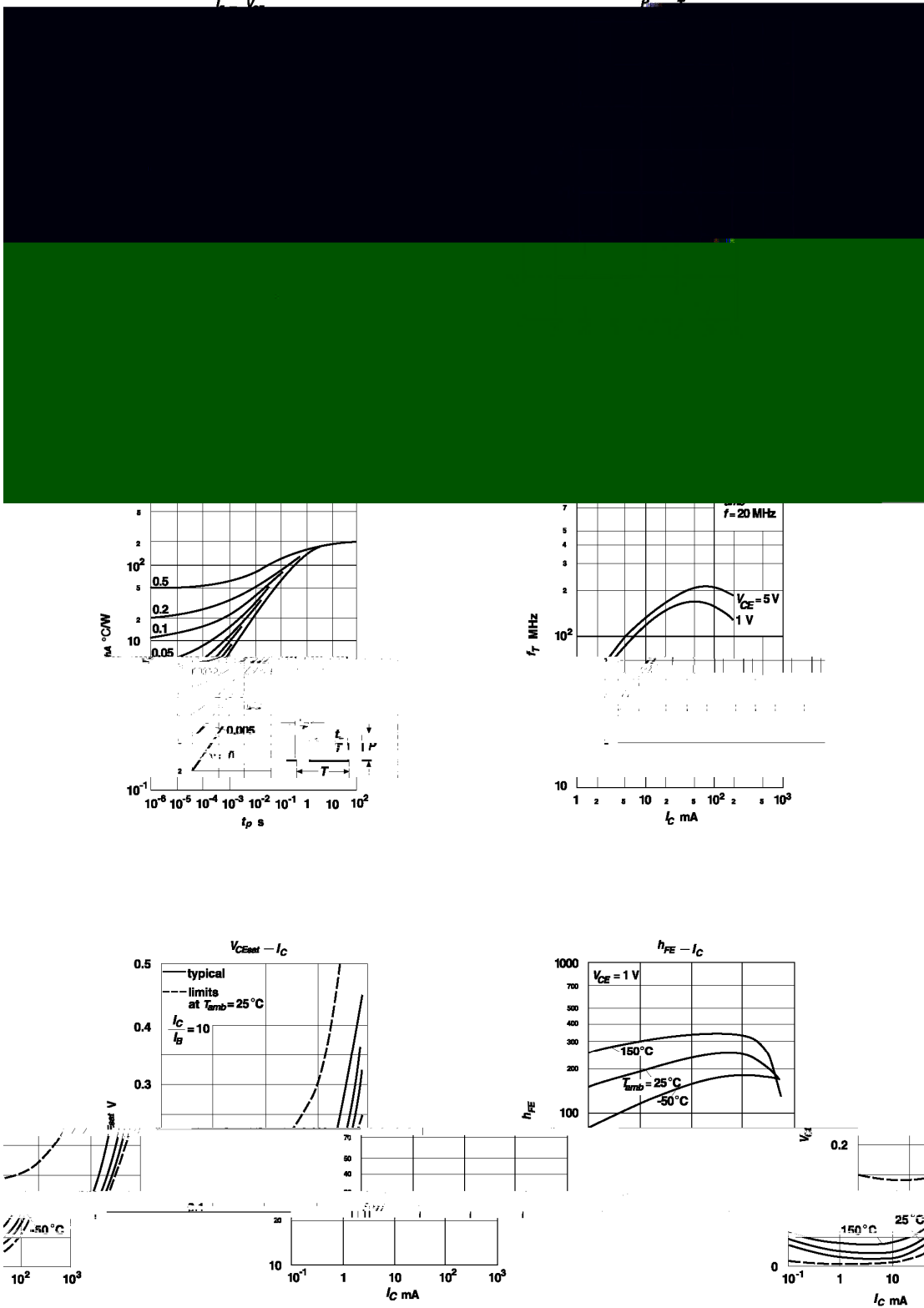
$h_{FE}$ Classifications Symbol	16	25	40
$h_{FE}$ Range	100~250	160~400	250~600
Marking	H6C1	H6C2	H6C4

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	50	V
Collector to Emitter Voltage	$V_{CEO}$	45	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current - Continuous	$I_C$	800	mA
Collector Emitter - Continuous	$I_E$	-800	mA
Collector Power Dissipation	$P_C$	300	mW
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55~150	

---

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
-----------	--------	-----------------	-----	-----	-----	------

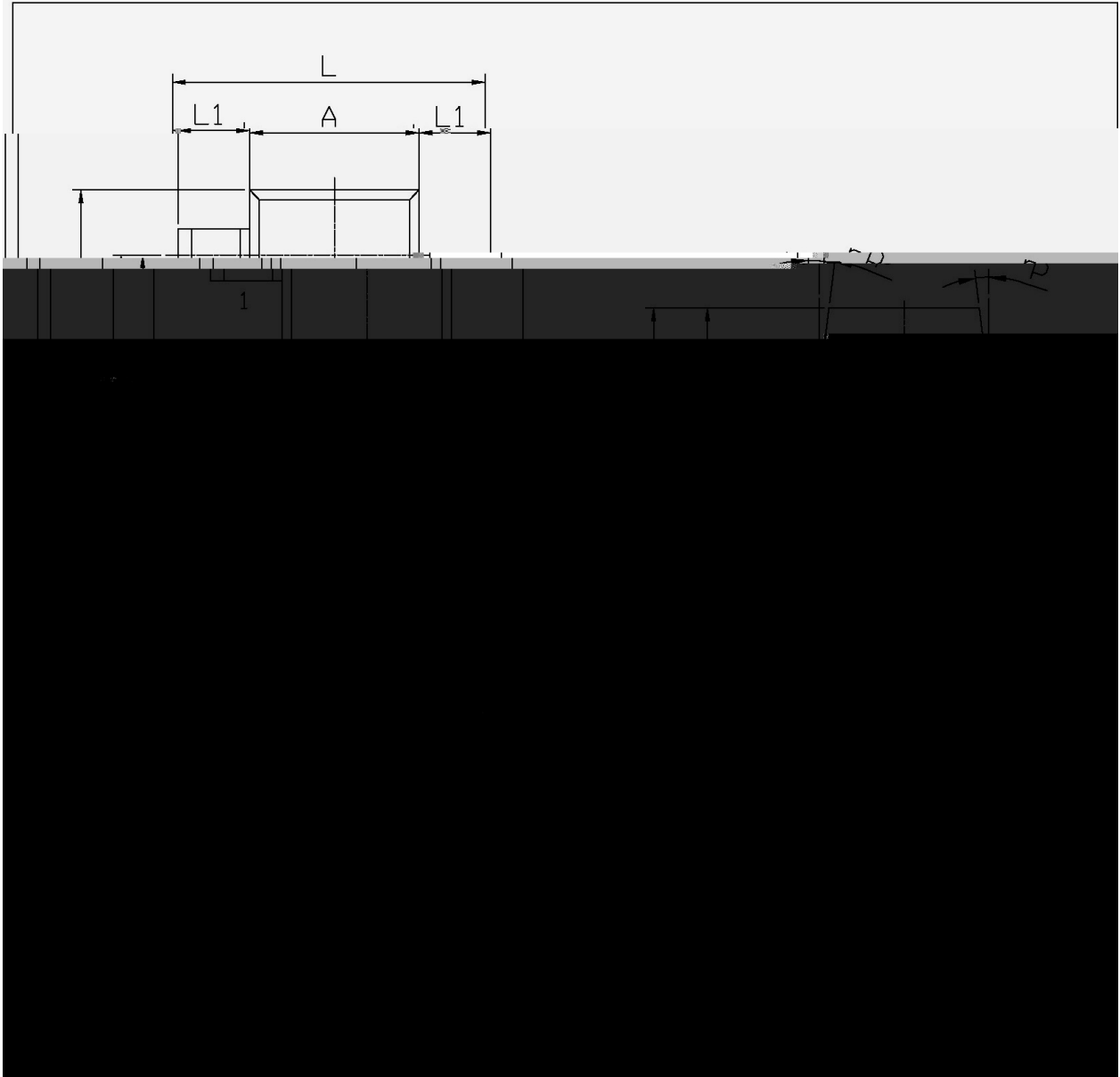
/ Electrical Characteristic Curve



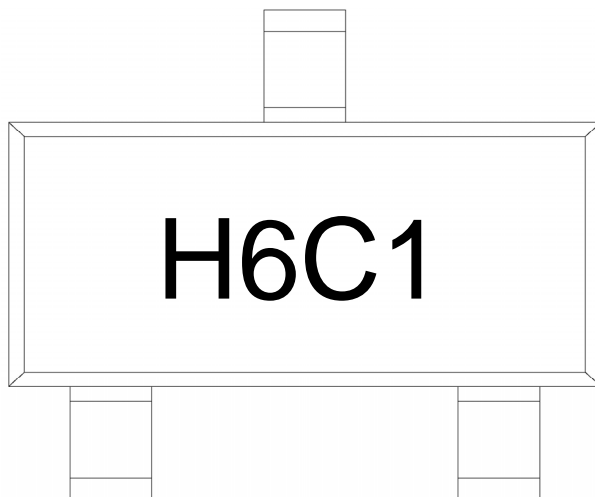
/ Package Dimensions

SOT-23

单位: mm



/ Marking Instructions



H

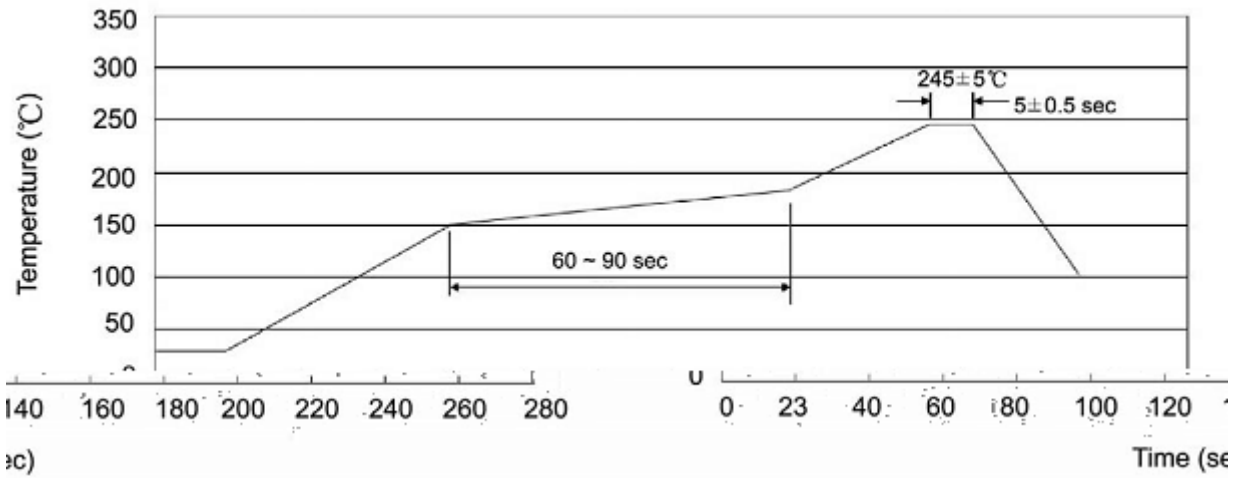
6C1

Note:

H: Company Code.

6C1: Product Type Code.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |    |           |   |
|---|-------|-----|----|-----------|---|
| 1 | 25    | 150 | 60 | 90sec;    | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     |    | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2  | 10 /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	只卷盘	卷盘盒	只盒	盒箱	只箱		盒	箱
						"		

/ Notices